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**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 47768-2026

**Micro-electromechanical systems (MEMS) technology - Bond
strength test for glass frit bonded structures using
micro-chevron-tests (MCT)**

微机电系统（MEMS）技术 玻璃浆料键合强度的微型V形试验（MCT）测量方法
(English Translation)

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This document complies with the provisions of GB/T 1.1-2020 "Standardization Work Guidelines Part 1: Structure and Drafting Rules of Standardization Documents".

Drafting.

This document is equivalent to IEC 62047-27:2017 "Semiconductor devices - Microelectromechanical devices - Part 27: Glass paste bonding strength".

"Measurement Method of Miniature V-Shaped Test (MCT)" the following minimal editorial changes have been made to this document.

---To harmonize with existing national standards, the standard name has been changed to "Bond Strength of Glass Slurry in Microelectromechanical Systems (MEMS) Technology".

Miniature V-T Test (MCT) Measurement Method.

Please note that some content in this document may involve patents. The issuing organization of this document assumes no responsibility for identifying patents.

This document was proposed and is under the jurisdiction of the National Technical Committee on Standardization of Microelectromechanical Systems (SAC/TC336).